We claim:

1. A layer sequence built on a substrate in thin-layer technology, said layer sequence comprising an electrically conductive sputtered layer (4) and an electrically conductive reinforcing layer (5) for reinforcing or strengthening the sputtered layer, said reinforcing layer (5) being applied by a method other than sputtering, wherein said electrically conductive reinforcing layer (5) is made a less effective reinforcing means for the sputtered layer in regions (6,10,14, 16, 17, 19) of said electrically conductive sputtered layer (4) to be adjusted than in other regions outside of said regions to be adjusted.

2. The layer sequence as defined in claim 1, wherein said electrically conductive reinforcing layer (5) is thinner in said regions (6,10,14, 16, 17, 19) of said electrically conductive sputtered layer (4) to be adjusted than in said other regions.

3. The layer sequence as defined in claim 1, wherein said electrically conductive sputtered layer (4) is made of gold.

4. The layer sequence as defined in claim 1, wherein said electrically conductive reinforcing layer (5) is made of gold.

5. The layer sequence as defined in claim 1, wherein said regions (14, 16, 17) of said electrically conductive sputtered layer (4) to be adjusted are located in portions of the layer sequence carrying less current than other portions.

6. The layer sequence as defined in claim 5, wherein at least one of said regions (14, 16, 17) of said electrically conductive sputtered layer (4) to be adjusted is located at an end of an open conducting line (13).

7. The layer sequence as defined in claim 2, wherein said other regions outside of said regions (14, 16, 17) of said electrically conductive sputtered layer (4) to be adjusted include contacting surfaces (11,12).

8. The layer sequence as defined in claim 1, wherein said regions (14, 16, 17) of said electrically conductive sputtered layer (4) to be adjusted are located on a side of said sputtered layer (4) opposite from said substrate (1).

9. A layer sequence built on a substrate in thin-layer technology, said layer sequence comprising an electrically conductive sputtered layer (4) and an electrically conductive reinforcing layer (5) for reinforcing or strengthening the sputtered layer, said reinforcing layer (5) being applied by a method other than sputtering, wherein said electrically conductive reinforcing layer (5) has a smaller thickness in regions (6,10,14, 16, 17, 19) of said electrically conductive sputtered layer (4) to be adjusted than in other regions outside of said regions to be adjusted.

10. The layer sequence as defined in claim 9, wherein said electrically conductive reinforcing layer (5) is eliminated from said regions (6,10,14, 16, 17, 19) of said electrically conductive sputtered layer (4) to be adjusted.

11. The layer sequence as defined in claim 9, wherein said sputtered layer (4) and said reinforcing layer (5) are both made of gold.